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**FUKUSHIMA et al.**(10) **Pub. No.: US 2022/0386458 A1**(43) **Pub. Date: Dec. 1, 2022**(54) **WIRING CIRCUIT BOARD AND  
PRODUCING METHOD THEREOF****Publication Classification**(51) **Int. Cl.**  
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CPC ..... **H05K 1/0296** (2013.01)(71) Applicant: **NITTO DENKO CORPORATION,**  
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(2) Date: **May 10, 2022**(57) **ABSTRACT**

A wiring circuit board includes a base insulating layer, a first wiring layer disposed at one side in a thickness direction of the base insulating layer, and a cover insulating layer disposed on one surface in the thickness direction of the base insulating layer so as to cover the first wiring layer. The first wiring layer includes a first wiring portion in contact with one surface of the base insulating layer, and a second wiring portion in contact with one surface in the thickness direction of the first wiring portion. Both end surfaces in a width direction perpendicular to the thickness direction and a transmission direction of the second wiring portion are disposed inside in the width direction with respect to both end surfaces of the first wiring portion.

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